

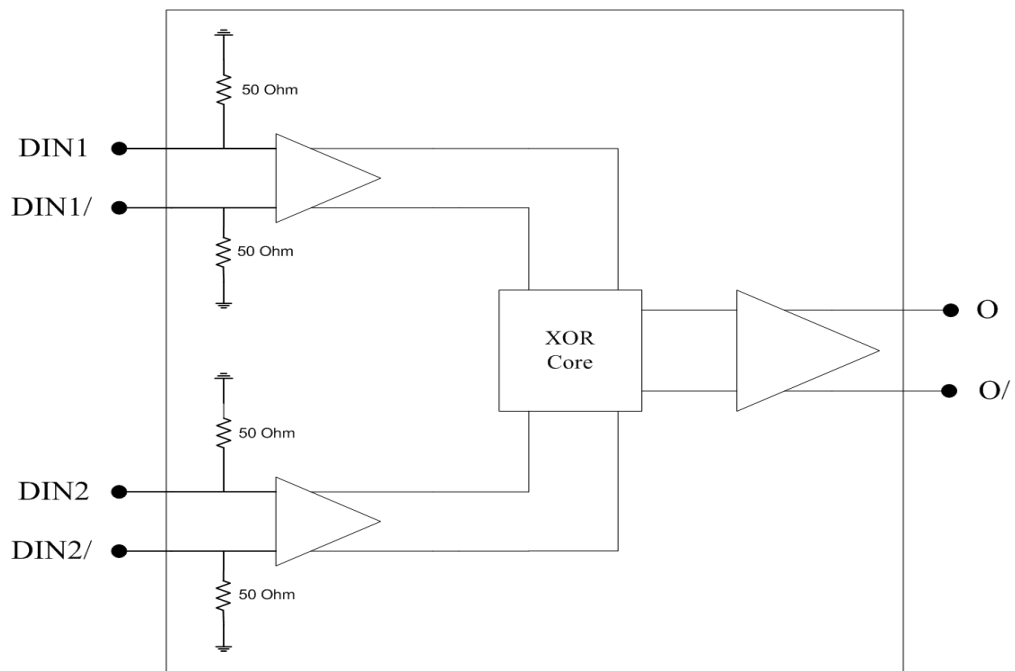
### Description

The DM4011 is a high-speed logic exclusive OR (XOR) device fabricated using 1- $\mu\text{m}$  GaAs HBT technology. It features high output voltage, fast rise and fall times, and excellent eye diagram at data rates up to 12.5 Gb/s. Applications include XOR logic up to 12.5 Gb/s, edge detection and Manchester encoding up to 10.709 Gb/s, and X2 clock multiplication with inputs up to 6.25 GHz. The DM4011 employs an ECL topology to guarantee high-speed operation. Data inputs and output are DC coupled, and internal 50-ohm resistors at the input eliminate the need for external impedance matching terminations. Inputs can be either single-ended or differential, and a high-performance output buffer ensure superior eye diagram performance.

### Features

- Data rate range: DC to 12.5 Gb/s
- Typical single-ended output : 800 mVpp
- Input sensitivity: >300 mV (single-ended)
- Jitter RMS < 1.8 ps
- Output rise time (20% to 80%): < 22 ps
- Output fall time (20% to 80%): < 19 ps
- 50-ohm matched DC-coupled inputs and outputs
- Differential or single-ended I/O
- Power consumption: 750 mW
- 4mm Plastic QFN Package or Die

### Device Diagram



### Disclaimer

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# DM4011

## 12.5 Gb/sec XOR gate

(Preliminary Information)

### Absolute Maximum Ratings

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only. Functional operation of the device at these or any other conditions above those indicated in the operational section of this document is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Symbol	Parameters/Conditions	Min.	Max.	Units
V <sub>ee</sub>	Power supply voltage	-5.5	0	V
V <sub>ih</sub>	Data/clock input voltage level, high level	-1.2	1.2	V
V <sub>il</sub>	Data/clock input voltage level, low level	-1.2	1.2	V
T <sub>a</sub>	Operating temperature range – die	-15	125	°C
T <sub>stg</sub>	Storage temperature	-65	150	°C

### Recommended Operating Conditions

Symbol	Parameters/conditions	Min.	Typ.	Max.	Units
T <sub>a</sub>	Operating temperature range – die	0		85	°C
V <sub>ee</sub>	Power supply voltage		-5		V
V <sub>ih</sub>	Data input voltage level, high level (single-ended)		0		V
V <sub>il</sub>	Data input voltage level, low level (single-ended)		-0.9		V
V <sub>indc</sub>	DC input voltage (with DC-coupled input)		-0.45		V

### Electrical Characteristics<sup>1</sup>

1. At ambient temperature

2. In the case of single-ended inputs, the unused one must be tied to  $V_{indc}$ . In the case of single-ended outputs, the unused one must be terminated with 50 ohms to ground.

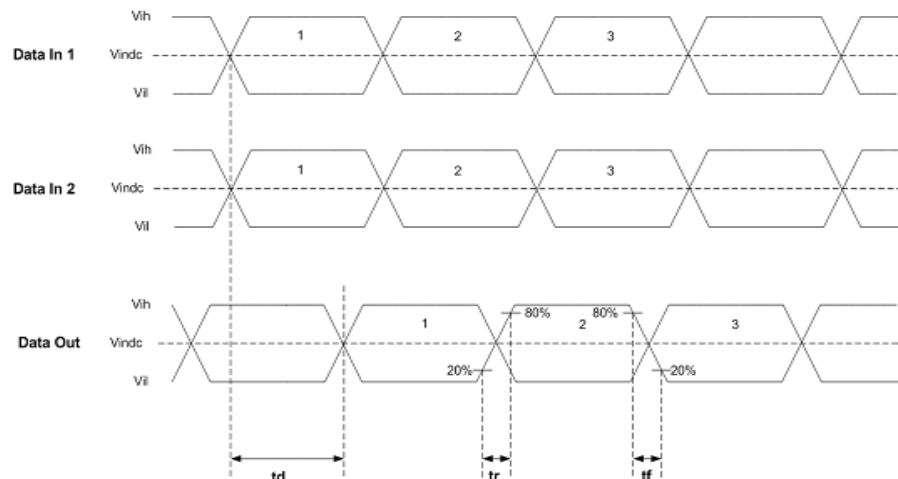
3. The output common mode is application dependent. The figures in the table do not apply when the DM4011 is used as an edge detector.

4. Simulated data.

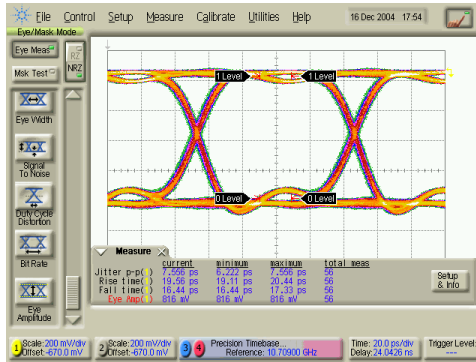
5.  $RL_{out}$  increases up to 9.5 dB by inserting a 10-ohm series resistor on the outputs.

Symbol	Parameters	Min	Typ	Max	Units	
$V_{cc}$	Power supply voltage	-5.25	-5.0	-4.75	V	
$V_{ih}$	Data input voltage level, high level (single-ended)	-0.5	0.0	0.5	V	
$V_{il}$	Data input voltage level, low level (single-ended)	-1	-0.9	0.0	V	
$V_{INpp}$	Data input amplitude	Differential peak-to-peak	0.3	1.8	2.0	V
		Single-ended peak-to-peak	0.3	0.9	1.0	V
$V_{indc}$	DC input voltage (with DC-coupled input) <sup>2</sup>	-0.75	-0.45	0.25	V	
$V_{out}$	Data output voltage amplitude (O,Ob) single-ended, peak-to-peak	0.7	0.8	0.85	V	
$V_{OH}$	Data output voltage high level (O, Ob) <sup>3</sup>	-0.1	0	--	V	
$V_{outc}$	Data output voltage, common mode (O, Ob) single-ended <sup>3</sup>	-0.4	-0.35	-0.3	V	
$T_r$	Output rise time (20% to 80%)		20	24	ps	
$T_f$	Output fall time (20% to 80%)		17	21	ps	
$T_d$	Data in to data out delay <sup>4</sup>		80		ps	
$RL_{in}$	Input return loss (up to 15 GHz) <sup>4</sup>		15		dB	
$RL_{out}$	Output return loss (up to 15 GHz) <sup>4,5</sup>		5		dB	
$J_{pp}$	Peak to peak jitter	4	7.7	10	ps	
$J_{rms}$	RMS jitter	0.82	1.3	1.8	ps	
$I_c$	Power supply current	137	150	162	mA	
$P_d$	Power dissipation	0.65	0.75	0.85	W	

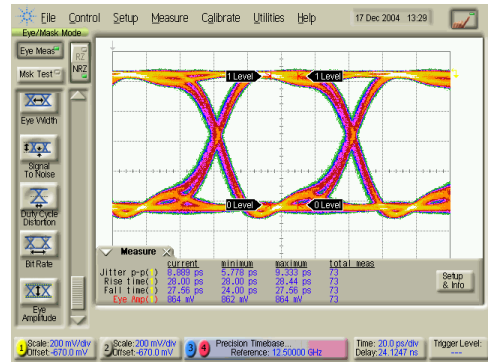
### Timing Diagram



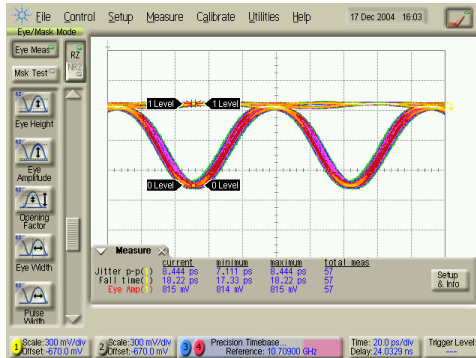
### Eye Diagram Performance



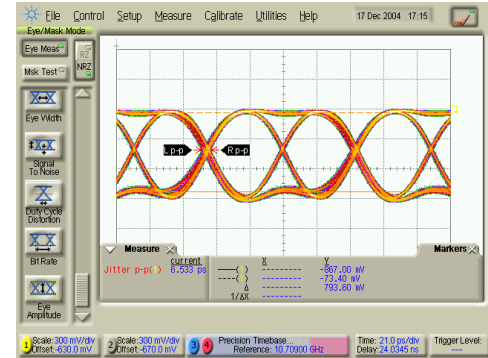
DM4011 used as XOR gate.  
10.709 Gb/s NRZ inputs,  
1.8 Vpp differential on DIN1 and DIN2.  
Power supply voltage: -5 V  
Power supply current: 150 mA  
Open frame



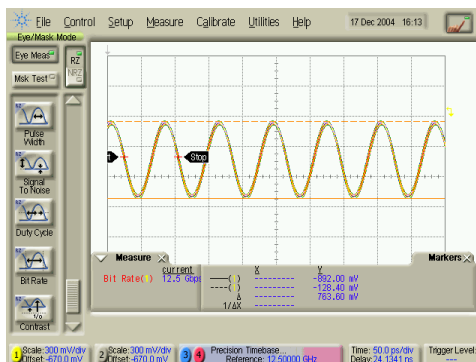
DM4011 used as XOR gate.  
12.5 Gb/s NRZ inputs,  
1.8 Vpp differential on DIN1 and DIN2.  
Power supply voltage: -5 V  
Power supply current: 150 mA  
Open frame



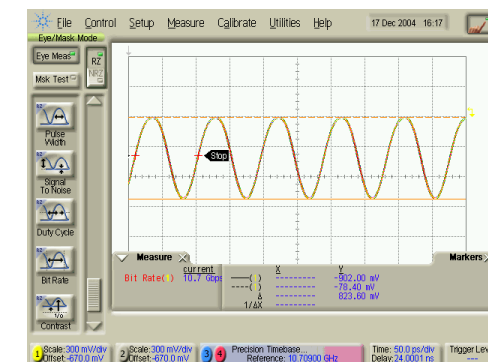
DM4011 used as edge detector.  
10.709 Gb/s NRZ inputs,  
1.8 Vpp differential on DIN1 and DIN2.  
Power supply voltage: -5 V  
Power supply current: 150 mA  
Open frame



DM4011 used as Manchester encoder.  
10.709 Gb/s NRZ inputs,  
1.8 Vpp differential on DIN1 and DIN2.  
Power supply voltage: -5 V  
Power supply current: 150 mA  
Open frame

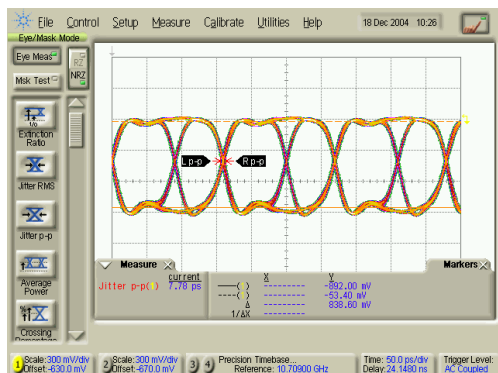


DM4011 used as X2 clock multiplier.  
6.25 GHz clock inputs, 1.8 Vpp differential on DIN1 and DIN2.  
Power supply voltage: -5 V  
Power supply current: 150 mA  
Open frame

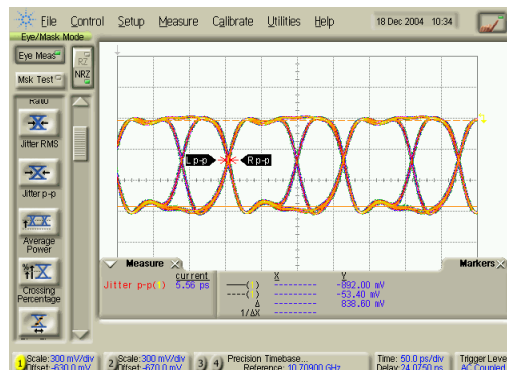


DM4011 used as X2 clock multiplier.  
5.36 GHz clock inputs, 1.8 Vpp Differential on DIN1 and DIN2.  
Power supply voltage: -5 V  
Power supply current: 150 mA  
Open frame

### Eye Diagram Performance (cont.)



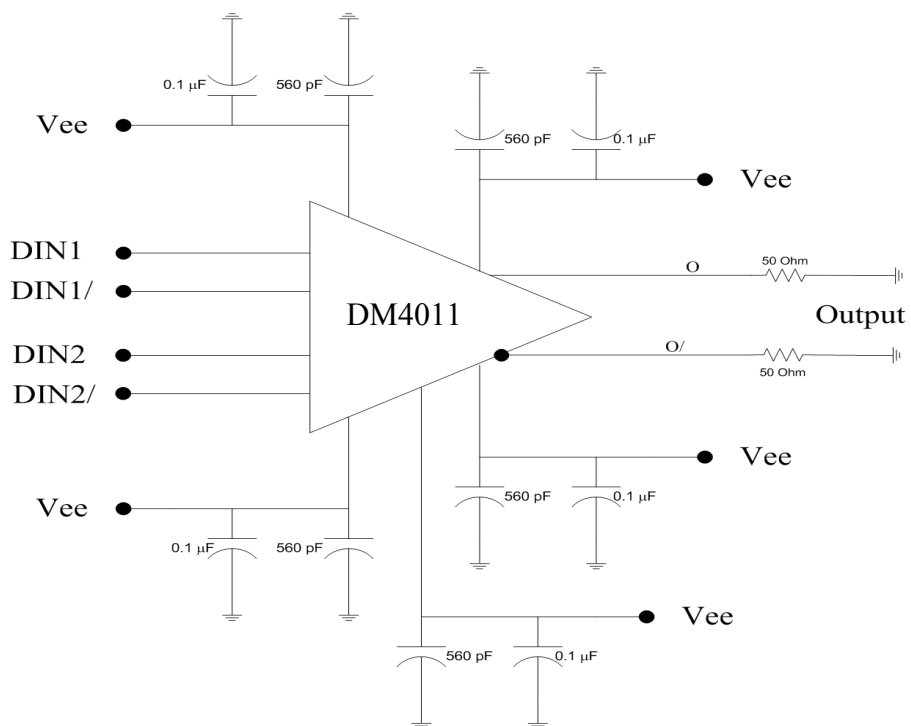
A.



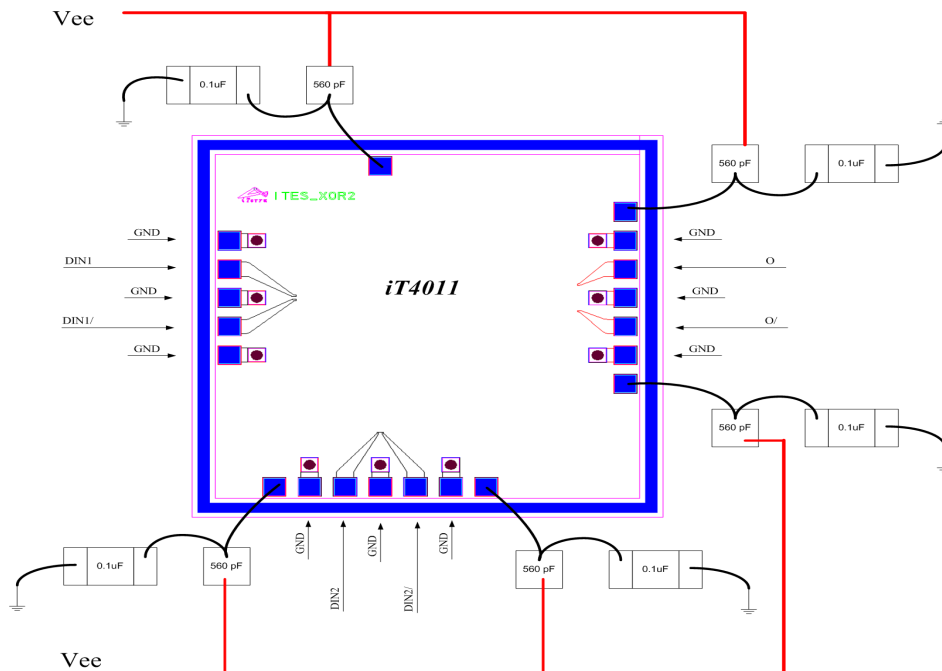
B.

DM4011 used as Manchester encoder with different input amplitudes,  
6.25 Gb/s NRZ inputs.  
A. 1.8 Vpp differential on DIN1 and DIN2.  
B. 0.6 Vpp differential on DIN1 and DIN2.  
Power supply voltage: -5 V  
Power supply current: 150 mA  
Open frame

### Recommended Operational Setup



### Recommended Chip Assembly



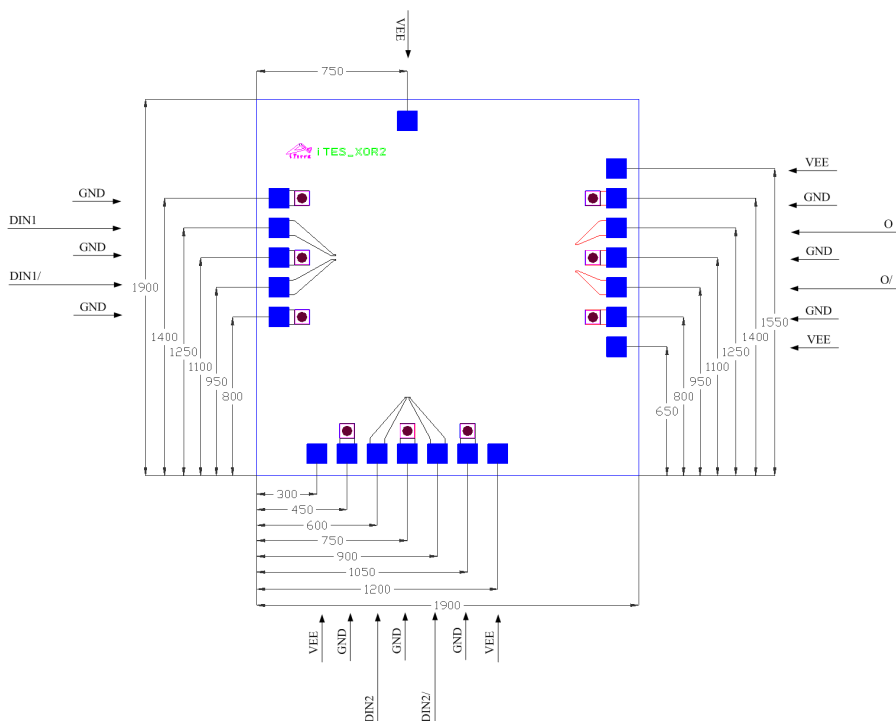
### Pads positions and chip dimension ( $\mu\text{m}$ )

Chip size:  
1900  $\mu\text{m}$  +/-10  $\mu\text{m}$   
x 1900  $\mu\text{m}$  +/-10  $\mu\text{m}$

Chip thickness:  
104  $\mu\text{m}$  +/-3  $\mu\text{m}$

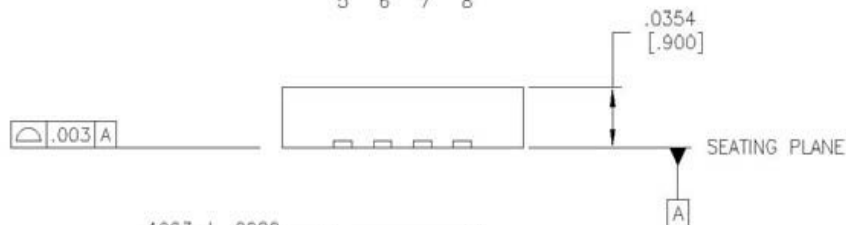
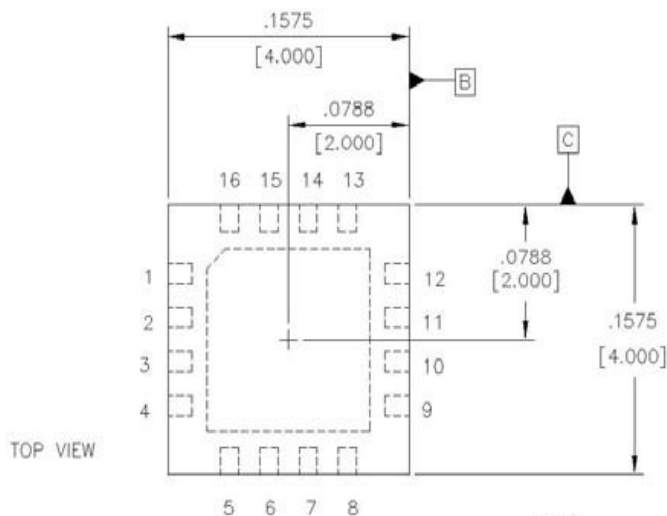
Pad size:  
100  $\mu\text{m}$  x 100  $\mu\text{m}$

RF pad pitch:  
150  $\mu\text{m}$



### Package Drawing and Pinouts

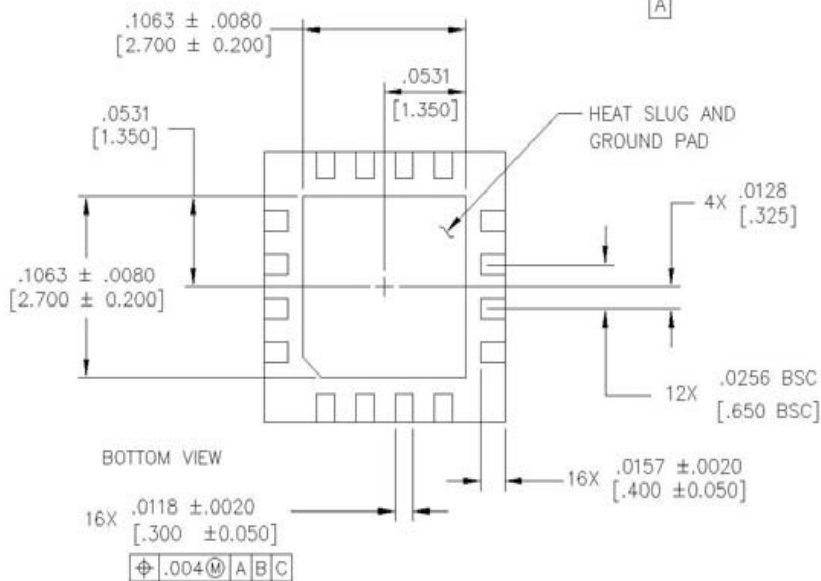
Dimension: Inches [mm]  
 Name equivalencies  
 A = Din1  
 B = Din2  
 Dout = Output  
 VEE=Power Supply



### Pinouts

P1: A  
 P2: N/C  
 P3: A/  
 P4: Vee  
 P5: B  
 P6: N/C  
 P7: B/  
 P8: N/C

P9: Vee  
 P10: Dout  
 P11: N/C  
 P12: Dout/  
 P13: Vee  
 P14: N/C  
 P15: N/C  
 P16: Vee





**DM4011**  
**12.5 Gb/sec XOR gate**  
**(Preliminary Information)**

**Application Information**

**CAUTION: THIS IS AN ESD SENSITIVE DEVICE**

Chip carrier material should be selected to have GaAs compatible thermal coefficient of expansion and high thermal conductivity such as copper molybdenum or copper tungsten. The chip carrier should be machined, finished flat, plated with gold over nickel and should be capable of withstanding 325°C for 15 minutes.

Die attachment for power devices should utilize Gold/Tin (80/20) eutectic alloy solder and should avoid hydrogen environment for HBT devices. Note that the backside of the chip is gold plated and it is connected to RF and DC Ground.

These GaAs devices should be handled with care and stored in dry nitrogen environment to prevent contamination of bonding surfaces. These are ESD sensitive devices and should be handled with appropriate precaution including the use of wrist-grounding straps. All die attach and wire/ribbon bond equipment must be well grounded to prevent static discharges through the device.

Recommended wire bonding: for Signal input / output connections, use either 3 mils wide and 0.5 mil thick gold ribbon or a pair of 1mil diameter wires with lengths as short as practical allowing for appropriate stress relief (typically 400 +/- 100 um long). For all other connections, a single 1 mil dia wire of appropriate minimum length may be used.

**Product Status Definitions**

Datasheet Identification	Product Status	Definition
Advanced Information	Formative or or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. DIGIMIMIC reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. DIGIMIMIC reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not in Production	This datasheet contains specifications on a product that has been discontinued by DIGIMIMIC. The datasheet is printed for reference information only.